

DesignNews

Exploring Electronic Circuits with Breadboards, AI Circuit Analysis, and Simulators

DAY 1 : Electronic Circuit Schematic Diagrams and Solderless Breadboards – New Perspective

Sponsored by









Webinar Logistics

- Turn on your system sound to hear the streaming presentation.
- If you have technical problems, click "Help" or submit a question asking for assistance.
- Participate in 'Attendee Chat' by maximizing the chat widget in your dock.







Dr. Don Wilcher

Visit 'Lecturer Profile' in your console for more details.





Course Kit and Materials

Adafruit Parts Pal Kit





Research Perspective

"Breadboards are widely used in early-stage circuit prototyping since they enable users to rapidly try out different components and to change the connections between them" (Zhu et al., 2020).





Agenda:

- The Solderless Breadboard Evolution
- The Solderless Breadboard Market
- The Solderless Breadboarding-New Perspectives
- How To Convert a Block Diagram to an Electronic Circuit Schematic Diagram?
- Lab: Build a Light Sensor with a 7 Segment LED Display



The Solderless Breadboard Evolution

- The Solderless Breadboard provides a foundational platform for:
 a) developing electronic circuit designs.
 b) testing electronic circuit designs.
- The main goal is to rapidly prototype an electronic circuit design without soldering components.
- The solderless breadboard construction consists of:
 a) plastic board with grid holes or cavities.
 b) grid holes or cavities are embedded within the plastic board.
- Before the solderless breadboard, electrical or electronic circuits were built using:
 - a) an actual breadboard.

Continuing Education

b) wood nails or Fahnestock clips to wire electrical and electronic components together.





The Solderless Breadboard Evolution





Image: Science Kit Store







Question 1

Before the solderless breadboard, electrical or electronic circuits were built using a simulated breadboard.



a) True

b) False





The Solderless Breadboard Evolution...

Circuit Building using Wooden Breadboards



Image: Adafruit Industries



Image: Sparkfun Electronics



DigiKey

The Solderless Breadboard Evolution...





DigiKey

The Solderless Breadboard Evolution...



Example Solderless Breadboard Product

Example Solderless Breadboard Product







The Solderless Breadboard Evolution...



BY Stone, Nierman,

Bottom Construction





DigiKey

The Solderless Breadboard Evolution...

228,136

BREADBOARD FOR ELECTRONIC COMPONENTS OR THE LIKE

Ronald J. Portugal, North Haven, Conn., assignor to El Instruments Incorporated, Derby, Conn.

Filed Dec. 1, 1971, Ser. No. 203,938

Term of patent 14 years

Int. Cl. D13-03

U.S. Cl. D26—1 R

Final Solderless Breadboard Design



FIG. 2







Question 2

Who was the inventor that received a patent on April 9, 1963, for the Device For Facilitating Construction of Electrical Apparatus?

- a) Ronald J. Portugal
- b) Rufus P. Turner

Continuing Education Center

- c) O.L. Thomas
- d) Forrest M. Mims





The Solderless Breadboard Evolution...

Mashup Solderless Breadboard Design





The Solderless Breadboard Market

Continuing Education

- The Brainy Insights (2024, May) reported the global Solderless Breadboard market was valued at 0.64 billion USD.
- The solderless breadboard market is expected to reach 0.97 billion USD by 2023.
- The Compound Annual Growth Rate (CARG) is 4.2% from 2024 to 2033.
- The potential drive behind the market is based on the following elements.
 a) DIY Projects growing demand
 - b) Educational programs (accounting for 50.34% of the growth rate)
 - c) Research and Development Initiatives
 - d) Technological advances in Online Sales for market expansion
 - i. Solderless breadboard technology has advanced to meet the changing demands of users.
 - ii. Developments in connectivity options, upgrades in power distribution mechanisms, and contact reliability impact solderless breadboard versatility and usage.



DigiKey

The Solderless Breadboard Market...

Solderless Breadboard Market Infographic







According to Brainy Insights (2024, May), the Solderless Breadboard Market should have a Compound Annual Growth Rate (CARG) of 5.2% from 2024 to 2033. a) False

b) True







Continuing Education

- Integrating breadboards into physical objects (Zhu et al., 2020) is being explored by HCI researchers.
 - b) promoting recycling and reuse of electronic thru-hole components.
- Design concepts for recycling and reuse of SMD components consist of:
 - a) using small Printed Circuit Board (PCB) elements that allow attaching leads or female header pins for mounting into solderless breadboards.
 - b) printing 3D housing that can mechanically mount SMDs into custom PCBs with female header pins for mounting into solderless breadboards (Yan et al., 2024).
 - c) Human-Computer Interaction (HCI) research in effective circuit assembly and disassembly of SMD and thru-hole components for solderless breadboards.







- The design goal of new solderless breadboard perspectives relates to:

 a) reuse of surface mount devices (SMDs) components.
 b) promoting recycling and reuse of electronic thru-hole components.
- Retro perspective solderless assembly (Fjelstad, n.d.) approaches for recycling and reuse of SMD components consist of:
 - a) twisted wire attachments.
 - b) wire wrapping.
 - c) press-fit pins.







CurveBoards Images: Zhu et al. (2020)







SolderlessPCB Image: Yan et al. (2020)

SNAP Elements and Modular Component PCBs









SolderlessPCB Image: Yan et al. (2020)



Question 4

The design goal of new solderless breadboards relates to:

- a) reuse of SMD and electronic thru-hole components
- b) reuse of SMD components and electromechanical parts
- c) reuse of materials and SMD components
- d) none of the above

Continuing Education





+5V

How To Convert a Block Diagram to an Electronic Circuit Schematic Diagram?







How To Convert a Block Diagram to an Electronic Circuit Schematic Diagram?...



Steps to Creating an Electronic Circuit Schematic Diagram from a Block Diagram.

- 1. Draw 4 levels of Block Diagrams to capture the target circuit's functional architecture.
- 2. Draw an Electronic Circuit for each block created in the Level 2 block diagram.
- 3. Label each electronic part with a Reference Designator (REF DES), part name, or value.



How To Convert a Block Diagram to an Electronic Circuit Schematic Diagram?...





Level 3



How To Convert a Block Diagram to an Electronic Circuit Schematic Diagram?...

Step 1: Functional Decomposition







DigiKey

How To Convert a Block Diagram to an Electronic Circuit Schematic Diagram?...

Steps 2 and 3: Alignment/Partitioning of Electronic Circuits with the Block Diagram and Documentation

















Lab Objectives:

- Participants will learn to capture parts data from a Block Diagram to construct an electronic circuit schematic diagram.
- Participants will learn to organize the wiring tasks in building a Light Sensor with a 7 Segment LED display on a solderless breadboard.
- Participants will wire and test the Light Sensor with a 7 Segment LED Display circuit on a solderless breadboard.





Level 2 Block Diagram and Bill of Materials (BOM) will help to capture parts and organize the wiring tasks for the project build.





Continuing Education Center

CEC

E:\Dwit	Icher F\Desig	nNews\CEC_c	courses/Sep	otember_20	24\Course_Sessions\Day1\Electronic_L	ght_Sensor_w_7_Segment_LED_Display\Electronic_Light_Sensor_w_7_Segment_LED_Display.kicad_sch
########						
I: Eeschema (6.0.4)						
or C:\Prog	gram Files\KiC	ad\6.0\bin\sc	ripting\plug	ins/bom_c	sv_grouped_by_value.py	
ne	8					
al Compo	nents:					
Oty	Reference	Value	LibPart	Footprint	Datasheet	
DISP1 HDSP-5503 Display_C Display_7 https://ia800903.us.archive.org/24/items/CTKD1x8K/Croma				Display 7	https://ia800903.us.archive.org/24/iten	Is/CTKD1x8K/Cromatek%20D168K.pdf
	PC1	CdS Cell	Device:R	Photo	~	
	Q1	PN2222	Device:Q	NPN EBC	~	
	R1	10K	Device:R	US	~	
	R2 560R		Device:R_US		~ A	A Bill of Material (BOM) for the
	R3	560R	Device:R	US	~	
	R4 560R		Device:R_US		~	Light Sensor with a 7 Segment
	R5	560R	Device:R	Device:R_US		LED Display project
						LED Display project.
Compon	ents'					
Compon	citto.					
Qty	Reference	Value	LibPart	Footprint	Datasheet	
1	1 DISP1 HDSP-5503		Display_C Display_7 https://ia800903.us.archive.org/24/items/CTKD1		https://ia800903.us.archive.org/24/iten	is/CTKD1x8K/Cromatek%20D168K.pdf
2	1 PC1	CdS Cell	Device:R	Photo	~	
3	1 Q1	PN2222	Device:Q	NPN_EBC	~	
4	1 R1	10K	Device:R	US	~	2/
5	4 R2, R3, R4	560R	Device:R	_US	~	
	e.towi ###### Eesche or C:\Prog ne al Compon Qty 1 2 3 4 5	e.utwitcher Proesig ######## Eeschema (6.0.4) or C:\Program Files\KiC ne 8 al Components: Qty Reference DISP1 PC1 Q1 R1 R2 R3 R4 R5 Components: Qty Reference 1 DISP1 2 PC1 Q1 R1 R2 R3 R4 R5 Qty Reference 1 DISP1 PC1 Q1 R1 R2 R3 R4 R5 Qty Reference 1 DISP1 PC1 Q1 R1 R1 R2 R3 R4 R5 Qty Reference Qty Reference 1 DISP1 PC1 Q1 R1 R2 R3 R4 R5 Qty Reference Qty R6 R6 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R5 R4 R5 R4 R5 R4 R5 R4 R5 R4 R5 R5 R4 R5 R5 R4 R5 R5 R4 R5 R4 R5 R5 R4 R5 R5 R4 R5 R5 R5 R5 R5 R5 R5 R5 R5 R5 R5 R5 R5	E.DWIICHE PUPEsignitews/CEC_C ####### Eeschema (6.0.4) or C:\Program Files\KiCad\6.0\bin\sc ne 8 al Components: 0 Qty Reference Value DISP1 HDSP-5503 PC1 CdS Cell Q1 PN2222 R1 10K R2 560R R3 560R R4 560R R5 560R Qty Reference Value I DISP1 HDSP-5503 1 Qty Reference Value I DISP1 HDSP-5503 2 I Q1 PN2222 1 I R1 I IOK	######## Eeschema (6.0.4) or C:\Program Files\KiCad\6.0\bin\scripting\plug ne 8 al Components: IbPart Qty Reference Value LibPart DISP1 HDSP-5503 Display_f PC1 CdS Cell Device:R Q1 PN2222 Device:R R1 10K Device:R R3 560R Device:R R4 560R Device:R R5 560R Device:R Qty Reference Value LibPart I DISP1 HDSP-5503 Display_f Qty Reference Value LibPart 1 DISP1 HDSP-5503 Display_f Qty Reference Value LibPart 1 DISP1 HDSP-5503 Display_f 2 1 PC1 CdS Cell Device:R 3 1 Q1 PN2222 Device:R 3 1 Q1 PN2222 Device:R 3 1 Q1	E.d.Witcher Process invews (CEC_courses (September_20) ######## Eeschema (6.0.4) or C:\Program Files\KiCad\6.0\bin\scripting\plugins/bom_cripting\plu	Provide Procession (Course Section (Course Sectin (Course Section (Course Section (Course Secti



Partitioning the Electronic Circuit Schematic diagram into circuit blocks will aid in the task of electrical wiring on a solderless breadboard.

Continuing

Education Center









36

Final Project Build: Solderless Breadboard on an Elephant (E) Breadboard!









A collimator was added to improve the light detection function of the CdS Photocell.







Watch the YouTube Video clip for the actual operation of the electronic detection circuit.



https://www.youtube.com/watch?v=Wlv9am4bftw





In reviewing slide 28, which circuit block diagram provides details of electronic components?

- a) Level 0
- b) Level 1
- c) Level 2
- d) Level 3







Thank you for attending

Please consider the resources below:

- The Brainy Insights. (2024, May). Solderless breadboards market. https://www.thebrainyinsights.com/report/solderless-breadboards-market-14339
- Yan, Z., Zhang, Z., Li, J., & Peng, H.(2023, May 21-16). SolderlessPCB: Reusing electronic components in pcb prototyping through detachable 3d printed housing [Conference session]. CHI, Honolulu, HI, United States. <u>https://arxiv.org/html/2403.18797v1</u>
- Zhu, J., Blumberg, L. G., Zhu, Y., Nisser, M., Carlson, E. L., Wen, X., Shum, K., Ayeley, J., & Meuller, S. (2020, April 25 -30). *CurveBoards: Integrating breadboards into physical objects to prototype function in the context of form* [Conference session]. CHI, Honolulu, HI, United States. <u>https://dl.acm.org/doi/abs/10.1145/3313831.3376617</u>



DesignNews

Thank You

Sponsored by



